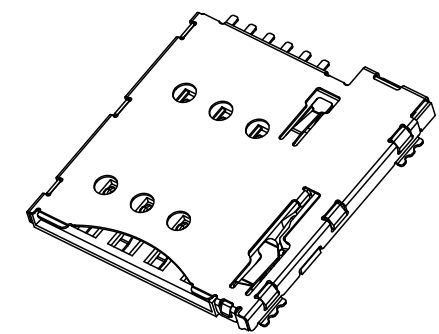
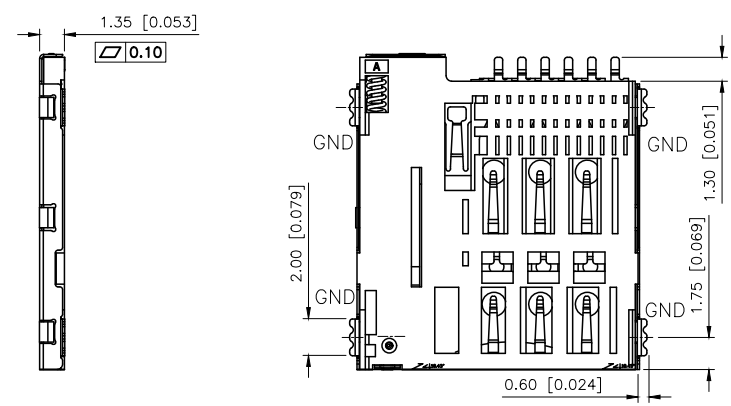
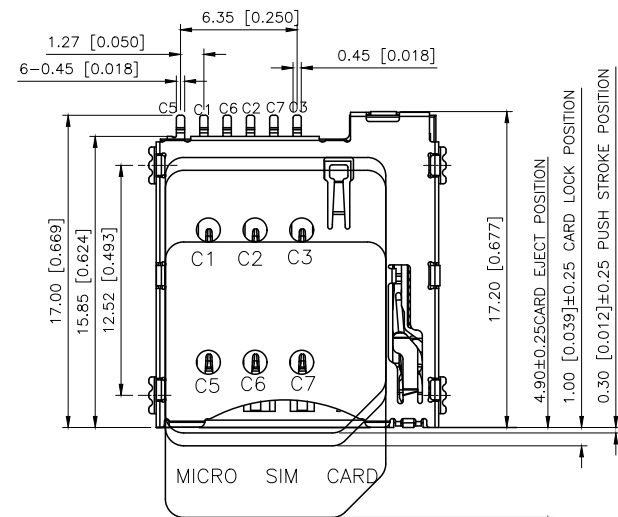
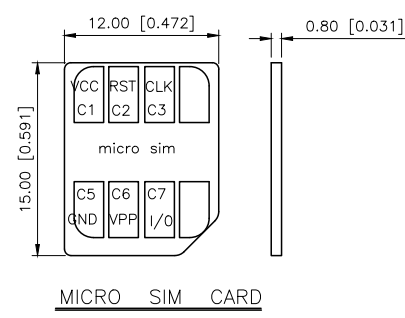
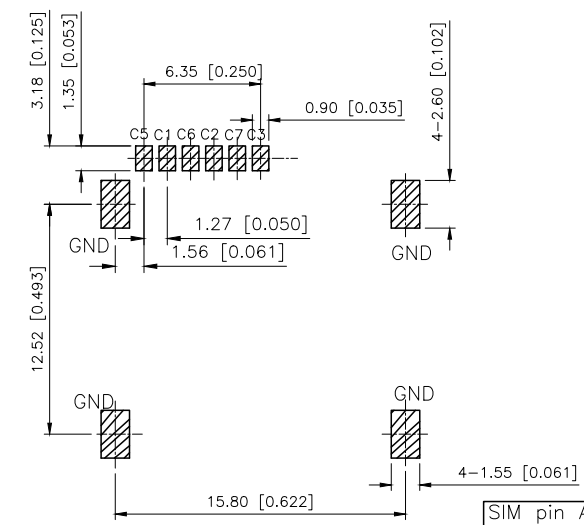
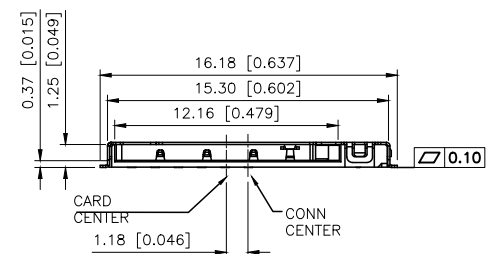


REVISIONS					
REV.	ECN NO.	LOCATION	DESCRIPTION	DATE	DESIGN
A0	N/A		INITIAL RELEASE	/	/
A1	N/A		图面升级整理图面	2025.05.15	阿树



NOTES:
MATERIAL:
Insulator: High Temperature Thermoplastic,
Contact: Copper Alloy
Shell: STAINLESS
PLATING:
Contact: Plated 30u" Ni Overall ,Solder Area:
Tin,Contact G/F
Shell: Plated 30u" Ni Overall
Plated G/F Selective Contact Area
Electrical:
Current Rating :0.5mA max.
Voltage Rating :50V DC MAX
Ambient Temperature Range : -20°C~+85°C
Storage Temperature Range : -40°C~+70°C
Ambient Humidity Range :95% R.H. Max.
Contact Resistance:100m max.
Insulation Resistance:1000M min./250V DC
Dielectric Withstanding Voltage:500V AC
Mating Cycles:5,000 Insertions
Temperature: 260°C ±5°



SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

RECOMMENDED PCB LAYOUT
GENERAL TOLERANCE ±0.05

■ CIRCUT TRACE KEEP OUT AREA
■ SMT SOLDER AREA
THERE SHOULD NOT BE ANY CIRCUITRIES
IN THE LAYOUT SPACE OF THE PRODUCTS.

AuGLAR	±5°
X.	±0.40
X.x	±0.30
X.xx	±0.20
X.xxx	±0.15
UNSPECIFIED TOLERANCES	



ITEM	PAPT NAME	QTY	MATERIAL	FINISHING
③	Shell	1	SUS	
②	Terminal	6	COPPER ALLOY	
①	Housing	1	HI-TEMP.PLASIC UL 94V-0	BLACK

DESIGN	阿树	VIEW:	MODEL TYPE: SIM CARD CONN
CHECKED		UNIT: mm/in	PART NO.: XKSIM-002-P6
APPROVED		SIZE: A4	DWG NO.: